



SPECIFICATION

• Supplier : Samsung electro-mechanics • Samsung P/N : CL31A475MAHNNNE

• Product : Multi-layer Ceramic Capacitor • Descriptiont : CAP, 4.7 µF, 25V, ±20%, X5R, 1206

A. Samsung Part Number

<u>CL</u> <u>31</u> <u>A</u> <u>475</u> <u>M</u> <u>A</u> <u>H</u> <u>N</u> <u>N</u> <u>N</u> <u>E</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

1	Series	Samsung Multi-layer Ceramic Capacitor										
2	Size	1206	(inch c	ode)	L: 3	.2	± 0.2	mm	W:	1.6	± 0.2	mm
						_						
③	Dielectric	X5R			(8	Inner e	electrode		Ni		
4	Capacitance	4.7	μF				Termin	nation		Cu		
⑤	Capacitance	±20	%				Plating	J		Sn 10	00%	(Pb Free)
	tolerance				(9	Produc	et		Norm	ıal	
6	Rated Voltage	25	V		(10	Specia	ıl		Rese	rved for	future use
7	Thickness	1.6	± 0.2	mm	(11)	Packag	ging		Embo	ossed T	ype, 7" reel

B. Samsung Reliability Test and Judgement condition

	Performance	Test condition						
Capacitance	Within specified tolerance	1kHz±10% 1.0±0.2Vrms						
Tan δ (DF)	0.075 max.							
Insulation	10,000Mohm or 500Mohm⋅μF	Rated Voltage 60~120 sec.						
Resistance	Whichever is Smaller							
Appearance	No abnormal exterior appearance	Microscope (×10)						
Withstanding	No dielectric breakdown or	250% of the rated voltage						
Voltage	mechanical breakdown							
Temperature	X5R							
Characteristics	(From -55℃ to 85℃, Capacitance change should be within ±15%)							
Adhesive Strength	No peeling shall be occur on the	500g⋅F, for 10±1 sec.						
of Termination	terminal electrode							
Bending Strength	Capacitance change : within ±12.5%	Bending to the limit (1mm)						
		with 1.0mm/sec.						
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder						
	is to be soldered newly	245±5°C, 3±0.3sec.						
		(preheating : 80~120 ℃ for 10~30sec.)						
Resistance to	Capacitance change: within ±7.5%	Solder pot : 270±5℃, 10±1sec.						
Soldering heat	Tan δ, IR : initial spec.							

	Performance		Test condition
Vibration Test	Capacitance change: withi	in ±5%	Amplitude : 1.5mm
	Tan δ, IR : initial spec.		From 10Hz to 55Hz (return : 1min.)
			2hours \times 3 direction (x, y, z)
Moisture	Capacitance change: withi	in ±12.5%	With rated voltage
Resistance	Tan δ: 0.125 max		40±2℃, 90~95%RH, 500+12/-0hrs
	IR : 12.5MΩ· <i>μ</i> F or Over		
High Temperature	Capacitance change: withi	in ±12.5%	With 150% of the rated voltage
Resistance	Tan δ: 0.125 max		Max. operating temperature
	IR : 25MΩ·μF or Over		
			1000+48/-0hrs
Temperature	Capacitance change: withi	in ±7.5%	1 cycle condition
Cycling	Tan δ, IR : initial spec.		Min. operating temperature \rightarrow 25 $^{\circ}$ C
			$ ightarrow$ Max. operating temperature $ ightarrow$ 25 $^{\circ}{ m C}$
			5 cycle test

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^{\circ}\text{C}$, 10sec. Max)

^{*} For the more detail Specification, Please refer to the Samsung MLCC catalogue.